

WHAT IS CLAIMED IS:

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1. An integrated circuit package comprising:
a printed circuit board;
a die attached to the printed circuit board; and
a heat spreader covering the die, the heat spreader contacting with
backside of the die and being mounted to the printed circuit board.

2. The integrated circuit package as claimed in claim 1, wherein the
heat spreader is formed by a piece body and a plurality of supporting
leads extended downward from a periphery of the piece body.

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3. The integrated circuit package as claimed in claim 2, wherein the
piece body of the heat spreader abuts on the backside of the die, an
interface with high thermal conductivity being filled between the piece
body and the die.

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4. The integrated circuit package as claimed in claim 3, wherein the
interface with high thermal conductivity is thermal grease.

5. The integrated circuit package as claimed in claim 2, wherein the
printed circuit board has a surface formed thereon a plurality of
thermal pads disposed around the die.

6. The integrated circuit package as claimed in claim 5, wherein the
plurality of supporting leads of the heat spreader are secured to the
plurality of thermal pads on the printed circuit board, respectively.

7. The integrated circuit package as claimed in claim 6, wherein the
plurality of supporting leads are secured to the plurality of thermal
pads by surface mounting technology.

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8. The integrated circuit package as claimed in claim 5, wherein the
printed circuit board defines a plurality of thermal via holes at
positions where the plurality of thermal pads are formed, respectively.

A 9. The integrated circuit package as claimed in claim 8, wherein the printed circuit board has an inner-layered copper plane, the plurality of thermal via holes being connected to the inner-layered copper plane.

A 10. The integrated circuit package as claimed in claim 5, wherein an additional heat sink is further mounted onto the piece body of the heat spreader.

A 11. The integrated circuit package as claimed in claim 5, wherein material with high thermal conductivity is filled between the plurality of supporting leads and the die.

10 12. The integrated circuit package as claimed in claim 1, wherein the material with high conductivity is thermal grease.